

U.S. Patent Application Serial No. 10/612,990  
Response filed March 8, 2005  
Reply to OA dated December 15, 2004

**REMARKS**

Claims 1 and 2 have been amended in order to more particularly point out, and distinctly claim the subject matter to which the applicant regards as his invention. The applicant respectfully submits that no new matter has been added. It is believed that this Amendment is fully responsive to the Office Action dated December 15, 2004.

Claims 1 and 2 are currently pending in this Divisional Application of U.S. Serial No. 09/789,771, claim 1 being an independent claim.

Claims 1 and 2 stand rejected under 35 USC §102(e) based on Hiraoka (U.S. Patent No. 6,465,742). The applicant respectfully requests reconsideration of this rejection.

The applicant's claimed invention, as now set forth in independent claim 1, is directed to a multilayer circuit board, having a plurality of cable layers, each of which includes electric conductive sections; a plurality of first insulating layers, each of which encloses said electric conductive sections in each cable layer and fills spaces between said electric conductive sections; and post vias electrically connecting said electric conductive sections in one cable layer to those in another cable

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layer. As now further recited independent claim 1, the height of the electric conductive sections in each cable layer are regulated by abrading to be equal to that of the first insulating layer enclosing those electric conductive sections.

A significant structural arrangement of the applicant's claimed multilayer circuit, as now set forth in independent claim 1, includes the height of the electric conductive sections in each cable layer being regulated by abrading to be equal to that of the first insulating layer enclosing those electric conductive sections.

On the other hand, in the Hiraoka reference, a circuit board is made by piling a plurality of sheet-shaped layers in which height of insulating layers enclosing electric conductive sections are equal.

As now set forth in independent claim 1, in the applicant's claimed multilayer circuit board, a plurality of the cable layers are piled, and the height of the electric conductive sections in each cable layer are regulated by abrading to be equal to that of the first insulating layer enclosing those electric conductive sections. Such claimed structural arrangement, as now recited in independent claim 1, is not disclosed in Hiraoka.

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Accordingly, the applicant respectfully submits that since not all of the claimed elements, as now recited in independent claim 1, are found in exactly the same situation and united in the same way to perform the identical function in Hiraoka's structure, there can be no anticipation under 35 USC §102(e) of the applicant's claimed multilayer circuit board, as now set forth in independent claim 1, based on Hiraoka.

Furthermore, claim 2 depends on independent claim 1, and further limits the scope of independent claim 1. Also, claim 2 now more particularly recites that the height of the post vias are regulated by abrading to be equal to that of the second insulating layer, a teaching not disclosed in Hiraoka. Thus, at least for the reasons set forth above with respect to claim 1, claim 2 should now be similarly allowable.

In view of the above, the withdrawal of the outstanding anticipation rejection under 35 USC §102(e) based on Hiraoka (U.S. Patent No. 6,465,742) is in order, and is therefore respectfully solicited.

In view of the aforementioned amendments and accompanying remarks, claims, as amended, are in condition for allowance, which action, at an early date, is requested.

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If, for any reason, it is felt that this application is not now in condition for allowance, the Examiner is requested to contact the applicant's undersigned attorney at the telephone number indicated below to arrange for an interview to expedite the disposition of this case.

In the event that this paper is not timely filed, the applicant respectfully petitions for an appropriate extension of time. Please charge any fees for such an extension of time and any other fees which may be due with respect to this paper to Deposit Account No. 01-2340.

Respectfully submitted,

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